



Product data sheet

1. General description

Planar passivated sensitive gate four quadrant triac in a SOT78 (TO-220AB) plastic package intended for use in general purpose bidirectional switching and phase control applications. This sensitive gate "series E" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- High blocking voltage capability
- Direct triggering from low power drivers and logic ICs
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- · Low holding current for low current loads and lowest EMI at commutation
- Sensitive gate

3. Applications

- General purpose motor control
- · General purpose switching

4. Quick reference data

Symbol	Parameter Conditions			Values		
Absolute	maximum rating					
V_{DRM}	repetitive peak off-state voltage			600		
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 102 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>	8		A	
I _{TSM}	non-repetitive peak on- state current	full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; <u>Fig. 4</u> ; <u>Fig. 5</u>	65		A	
Symbol	Parameter	Conditions	Min Typ Max		Max	Unit
Static ch	aracteristics		· ·	·		
I _{GT} gate trigger current	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 7</u>	-	2.5	10	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 7</u>	-	4	10	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u>	-	5	10	mA
		V _D = 12 V; I _T = 0.1 A; T2- G+; T _j = 25 °C; <u>Fig. 7</u>	-	11	25	mA
I _H	holding current	V _D = 12 V; T _i = 25 °C; <u>Fig. 9</u>	_	2.5	20	mA

5. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	
2	T2	main terminal 2	ך ⊖ ך	
3	G	gate		sym051
mb	T2	mounting base; main terminal 2		symus i

6. Ordering information

Table 3. Ordering information					
Type number Package					
	Name	Description	Version		
BT137-600E TO-220AB		plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78		

7. Marking

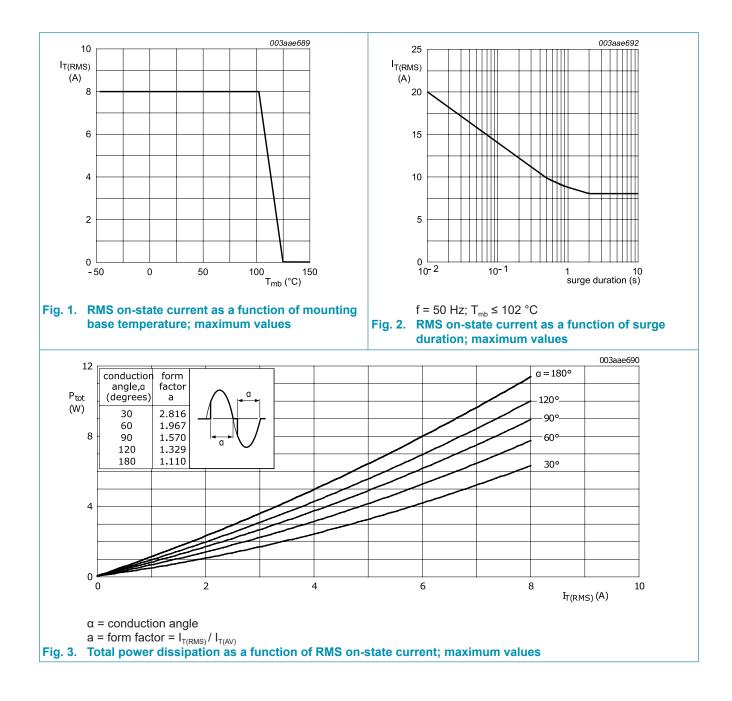
Table 4. Marking codes			
Type number	Marking codes		
BT137-600E	BT137-600E		

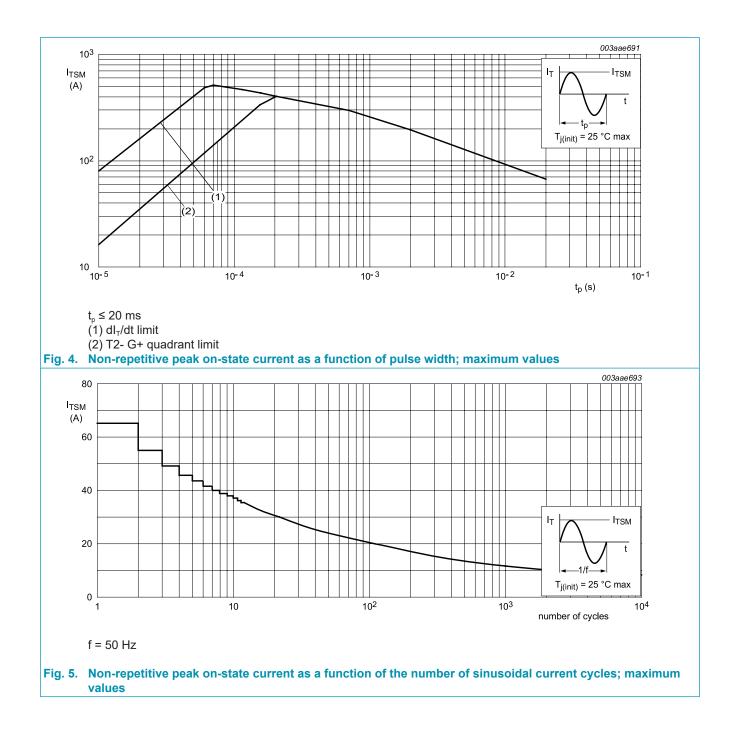
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

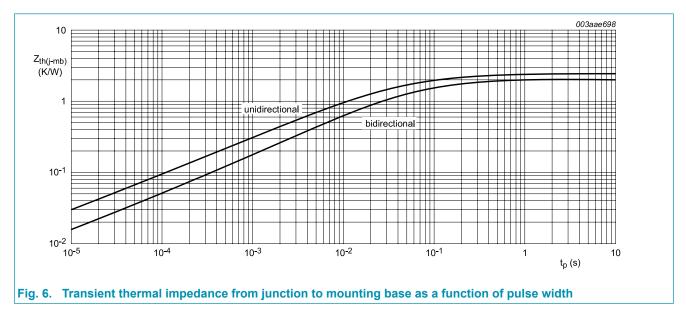
Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		600	V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 102 °C; <u>Fig 1; Fig 2; Fig 3</u>	8	A
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)} = 25 \text{ °C};$ $t_p = 20 \text{ ms}; Fig 4; Fig 5$	65	A
		full sine wave; $T_{j(init)} = 25 \text{ °C};$ $t_p = 16.7 \text{ ms}$	71	A
l ² t	I ² t for fusing	t _p = 10 ms; SIN	21	A ² s
dl _T /dt rate of rise of or current	rate of rise of on-state	I _G = 20 mA; T2+ G+	50	A/µs
	current	I _G = 20 mA; T2+ G-	50	A/µs
		I _G = 20 mA; T2- G-	50	A/µs
		I _G = 50 mA; T2- G+	10	A/µs
I _{GM}	peak gate current		2	А
P _{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T _{stg}	storage temperature		-40 to 150	°C
Tj	junction temperature		125	°C





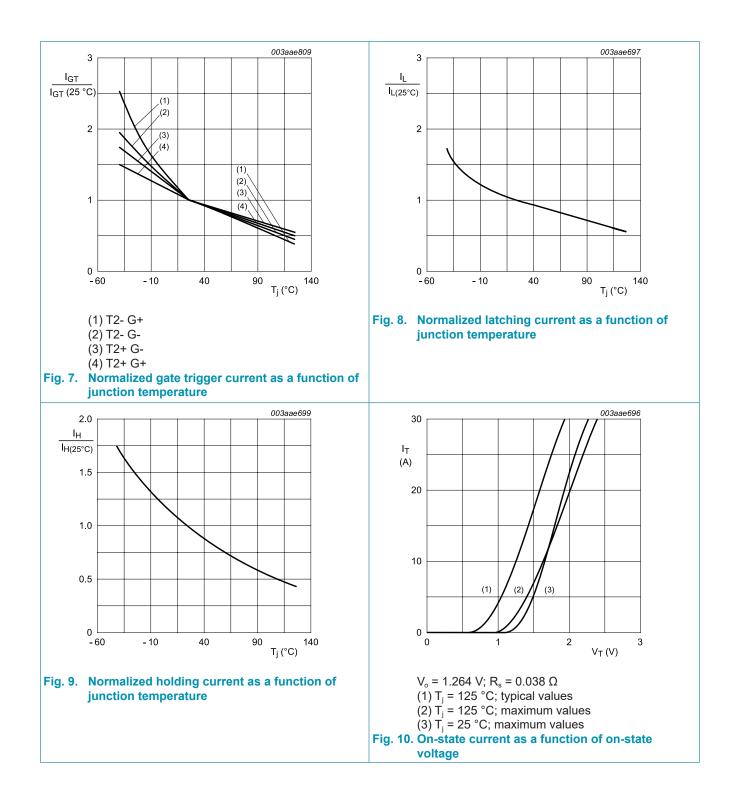
9. Thermal characteristics

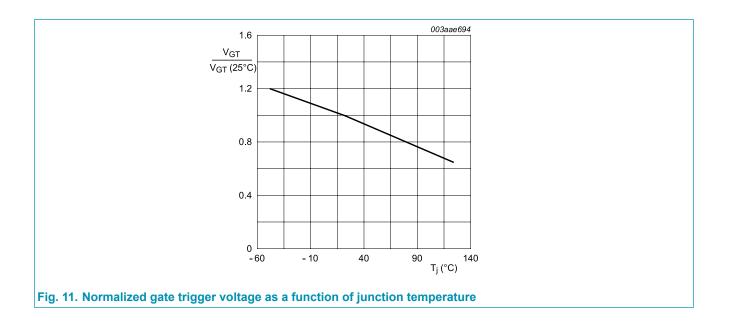
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	full cycle; <u>Fig 6</u>	-	-	2	K/W
		half cycle; <u>Fig 6</u>	-	-	2.4	K/W
R _{th(i-a)} thermal resistance from junction to ambient		in free air	-	60	-	K/W



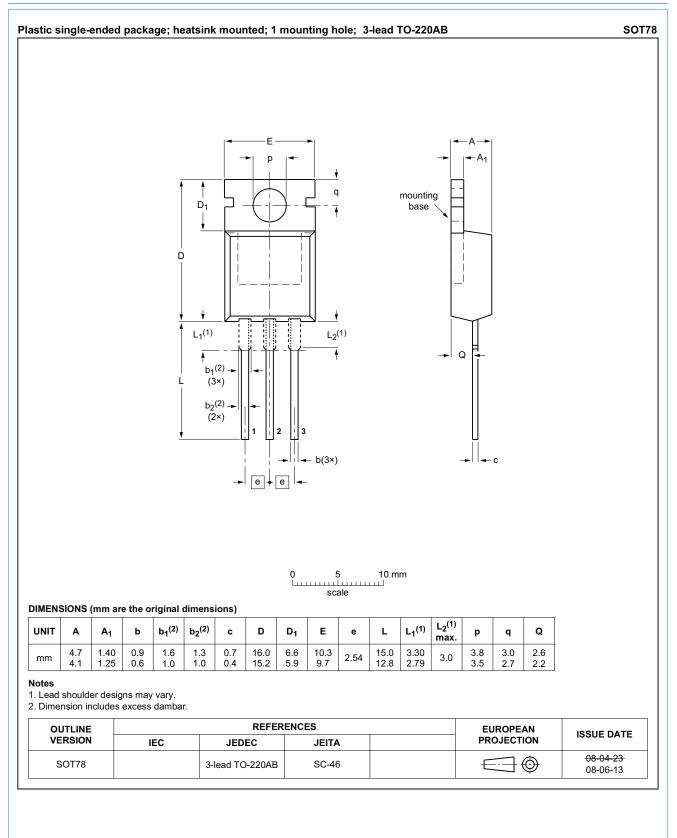
10. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics	· · · · · ·				
I _{GT}	gate trigger current	$V_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}; \text{ T2+ G+};$ $T_{j} = 25 \text{ °C}; \text{ Fig. 7}$	-	2.5	10	mA
		V_{D} = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 7</u>	-	4	10	mA
		$V_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}; \text{ T2- G-};$ $T_{j} = 25 \text{ °C}; \text{ Fig. 7}$	-	5	10	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2- G+};$ $T_j = 25 \text{ °C}; \text{ Fig. 7}$	-	11	25	mA
IL	latching current	$V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2+ G+};$ T _j = 25 °C; <u>Fig. 8</u>	-	3	25	mA
		$V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2+ G-};$ T _j = 25 °C; <u>Fig. 8</u>	-	14	35	mA
		$V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2- G-};$ T _j = 25 °C; <u>Fig. 8</u>	-	3	25	mA
		$V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2- G+};$ T _j = 25 °C; <u>Fig. 8</u>	-	4	35	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	2.5	20	mA
V _T	on-state voltage	I _T = 10 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.3	1.65	V
V _{GT}	gate trigger voltage	$V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T}_{j} = 25 \text{ °C};$ Fig. 11	-	0.7	1	V
		V _D = 400 V; I _T = 0.1 A; T _j = 125 °C; Fig. 11	0.25	0.4	-	V
I _D	off-state current	V _D = 600 V; T _j = 125 °C	-	0.1	0.5	mA
Dynamic	characteristics	· · · · ·	I			
dV _D /dt	rate of rise of off-state voltage	$V_{DM} = 402 \text{ V}; \text{ T}_{\text{j}} = 125 \text{ °C}; (V_{DM} = 67\% \text{ of } V_{DRM}); exponential waveform; gate open circuit - 50$		50	-	V/µs
t _{gt}	gate-controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = 600 \text{ V}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	μs





11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <u>http://www.ween-semi.com</u>.

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